

ABSTRACT

A through via includes a closed portion that closes a through hole at least at a minimum portion of the through hole, a third portion that is located on a wall surface of the through hole between a first surface and the closed portion, and a fourth portion that is located on the wall surface of the through hole between a second surface and the closed portion. A resin layer includes a first resin layer that is located inside the third portion and a second resin layer that is located inside the fourth portion. The through via has a first distance that is a maximum value of a distance from the first surface to the closed portion in a thickness direction of a substrate and a second distance that is a maximum value of a distance from the second surface to the closed portion in the thickness direction of the substrate. A ratio of the first distance to a thickness of the substrate is 0.10 or more. A ratio of the second distance to the thickness of the substrate is 0.10 or more.